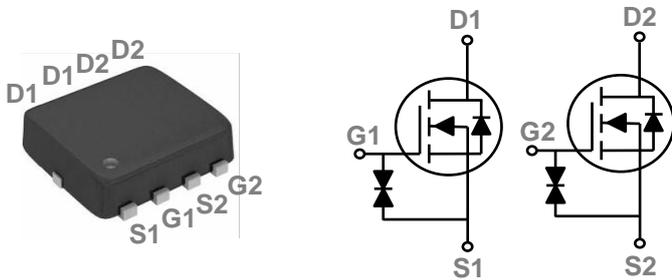


**General Description**

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
20V	12mΩ	30A

**PPAK3x3 Dual Pin Configuration**



**Features**

- 20V,30A, RDS(ON) =12mΩ @VGS = 10V
- Improved dv/dt capability
- ESD Protection Diode Embedded
- 100% EAS Guaranteed
- Green Device Available

**Applications**

- MB / VGA / Vcore
- POL Applications
- SMPS 2<sup>nd</sup> SR
- Li-Battery Protection

**Absolute Maximum Ratings** Tc=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	20	V
V <sub>GS</sub>	Gate-Source Voltage	±10	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>C</sub> =25°C)	30	A
	Drain Current – Continuous (T <sub>C</sub> =100°C)	19	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	120	A
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> =25°C)	26	W
	Power Dissipation – Derate above 25°C	0.21	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Characteristics**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	4.8	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**  
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	20	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	0.02	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =16V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V	---	---	±100	nA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	8	10	12	mΩ
		V <sub>GS</sub> =4.2V, I <sub>D</sub> =10A	8	10.1	12.2	mΩ
		V <sub>GS</sub> =3.7V, I <sub>D</sub> =9A	8	10.3	12.5	mΩ
		V <sub>GS</sub> =3.0V, I <sub>D</sub> =9A	8.5	10.7	13.2	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =8A	9	11.4	14.5	mΩ
		V <sub>GS</sub> =1.8V, I <sub>D</sub> =8A	10	15	20	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	0.3	0.6	1	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	2	---	mV/°C
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>S</sub> =5A	---	12	---	S

**Dynamic and switching Characteristics**

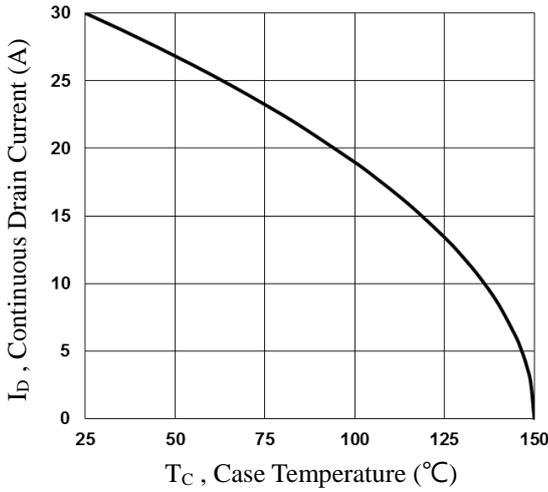
Q <sub>g</sub>	Total Gate Charge <sup>2,3</sup>	V <sub>DS</sub> =10V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A	---	16.9	26	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2,3</sup>		---	1.1	3	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2,3</sup>		---	4	7	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2,3</sup>	V <sub>DD</sub> =10V, V <sub>GS</sub> =4.5V, R <sub>G</sub> =25Ω I <sub>D</sub> =1A	---	6.8	13	ns
T <sub>r</sub>	Rise Time <sup>2,3</sup>		---	20	38	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2,3</sup>		---	41.8	79	
T <sub>f</sub>	Fall Time <sup>2,3</sup>		---	13.2	25	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, F=1MHz	---	1020	1480	pF
C <sub>oss</sub>	Output Capacitance		---	160	240	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	110	160	
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	---	2	4	Ω

**Drain-Source Diode Characteristics and Maximum Ratings**

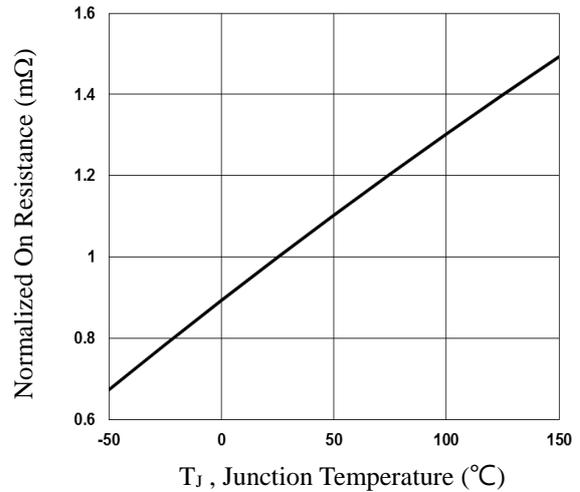
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	30	A
I <sub>SM</sub>	Pulsed Source Current		---	---	60	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1	V

Note :

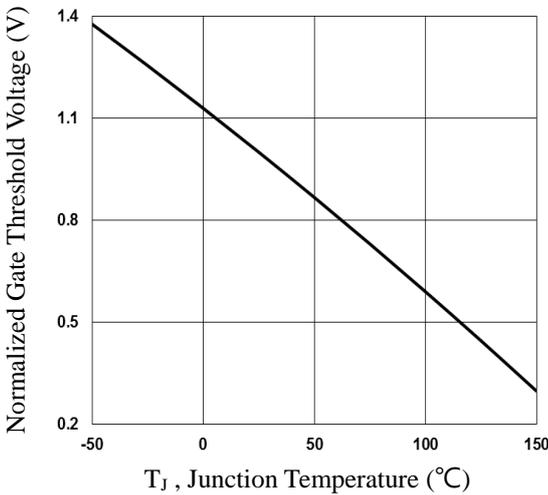
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.



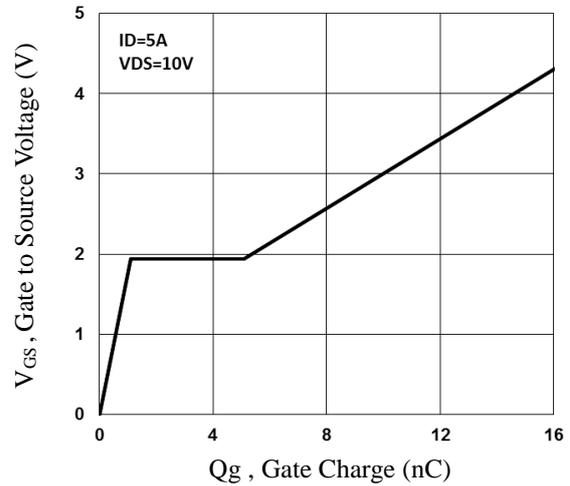
**Fig.1 Continuous Drain Current vs.  $T_c$**



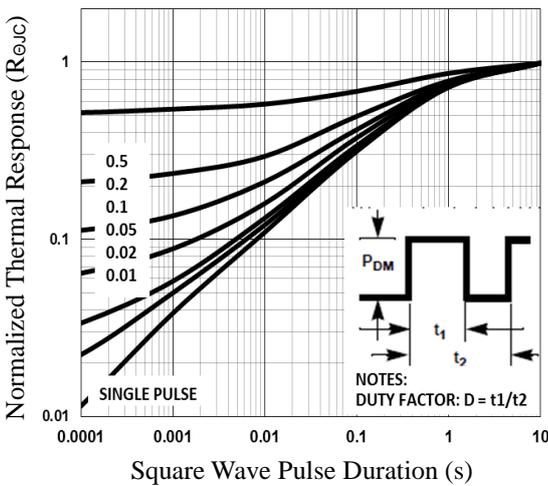
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$**



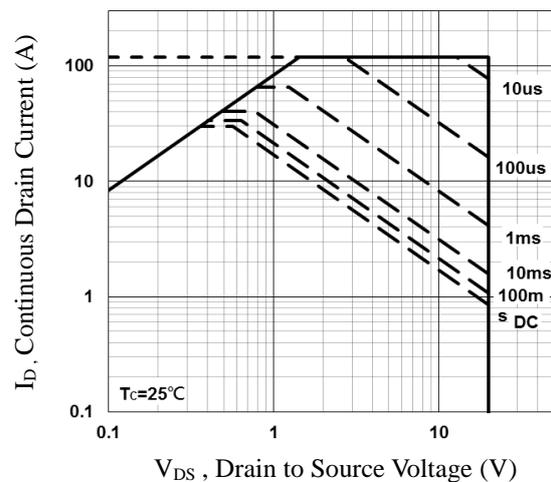
**Fig.3 Normalized  $V_{th}$  vs.  $T_j$**



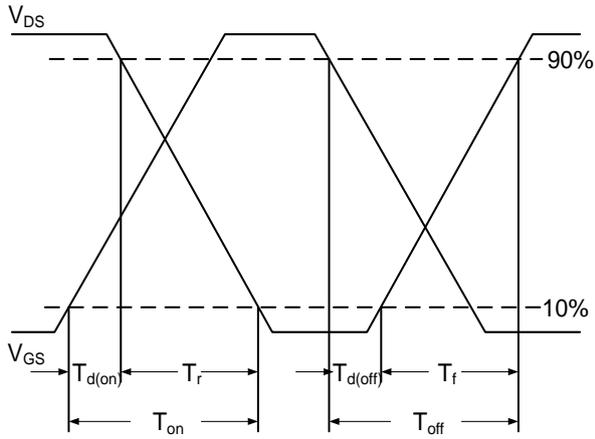
**Fig.4 Gate Charge Waveform**



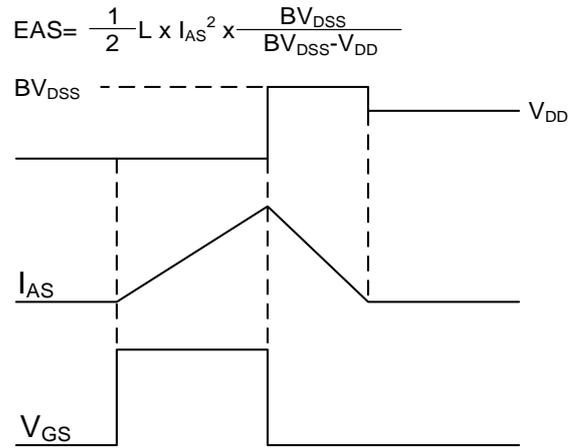
**Fig.5 Normalized Transient Response**



**Fig.6 Maximum Safe Operation Area**

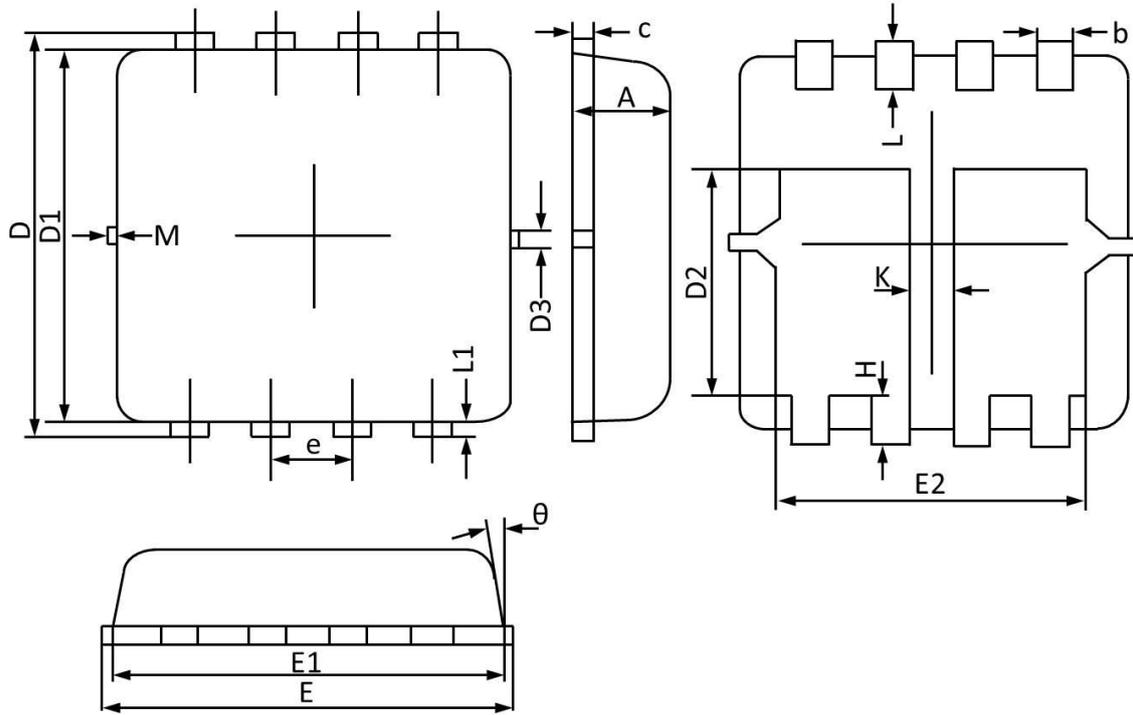


**Fig.7 Switching Time Waveform**



**Fig.8 EAS Waveform**

**PPAK3x3 Dual PACKAGE INFORMATION**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
b	0.250	0.350	0.010	0.013
c	0.100	0.250	0.004	0.009
D	3.250	3.450	0.128	0.135
D1	3.000	3.200	0.119	0.125
D2	1.780	1.980	0.070	0.077
D3	0.130 REF		0.005 REF	
E	3.200	3.400	0.126	0.133
E1	3.000	3.200	0.119	0.125
E2	2.390	2.590	0.094	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.500	0.011	0.019
L	0.300	0.500	0.011	0.019
L1	0.130 REF		0.005 REF	
K	0.300 REF		0.012 REF	
$\theta$	0°	12°	0°	12°
M	0.150 REF		0.006 REF	